100 mA, 5.0 V, Low Dropout Voltage Regulator with Reset and Sense

The NCV4949A is a monolithic integrated 5.0 V voltage regulator with a very low dropout and additional functions such as reset and an uncommitted voltage sense comparator.

It is designed for supplying microcontroller/microprocessor controlled systems particularly in automotive applications. The NCV4949A has improved reset behavior for lower input and output voltage levels.

Features

- Operating DC Supply Voltage Range 5.0 V to 28 V
- Transient Supply Voltage Up to 40 V
- High Precision Output Voltage 5.0 V $\pm 1\%$
- Output Current Capability Up to 100 mA
- Very Low Dropout Voltage Less Than 0.4 V
- Reset Circuit Sensing The Output Voltage
- Programmable Reset Pulse Delay
- Voltage Sense Comparator
- Thermal Shutdown and Short Circuit Protections
- AEC-Q100 Grade 1 Qualified and PPAP Capable
- These are Pb–Free Devices



Figure 1. Representative Block Diagram



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ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
DC Operating Supply Voltage (Note 1)	V _{CC}	28	V
Transient Supply Voltage (t < 1.0 s) (Note 2)	V _{CC TR}	40	V
Output Current	I _{out}	Internally Limited	-
Output Voltage (Note 1)	V _{out}	20	V
Sense Input Current	۱ _{SI}	±1.0	mA
Sense Input Voltage (Note 1)	V _{SI}	V _{CC}	-
Output Voltages (Note 1)			V
Reset Output	V _{Reset}	20	
Sense Output	V _{SO}	20	
Output Currents			mA
Reset Output	I _{Reset}	5.0	
Sense Output	I _{SO}	5.0	
Preregulator Output Voltage (Note 1)	VZ	7.0	V
Preregulator Output Current	Ι _Ζ	5.0	mA
Reset Delay Voltage (Note 1)	CT	7.0	V
Reset Delay Current	CT	Internally Limited	-
ESD Protection at any pin			V
Human Body Model	-	4000	
Machine Model	-	200	
Charged Device Model (SOIC-20 W)	-	1000	
Thermal Resistance, Junction-to-Air	R _{θJA}		°C/W
SOIC–8 SOIC–8 EP SOIC–20 W		189.3 84.8 95.8	
Operating Junction Temperature Range	TJ	-40 to +150	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Absolute negative voltage on these pins not to go below -0.3 V.

Load Dump Test B (with centralized load dump suppression) according to ISO16750–2 standard. Guaranteed by design. Not tested in production. Passed Class B (V_{out} < 5.5 V) according to ISO16750–1.

LEAD TEMPERATURE SOLDERING REFLOW (Note 3)

Rating	Symbol	Min	Max	Unit
Reflow (SMD styles only) lead free 60 – 150 sec above 217, 40 sec max at peak	Tsld	-	260	°C
Moisture Sensitivity Level (SOIC-8)	MSL	Level 1		
Moisture Sensitivity Level (SOIC-8EP)	MSL	Level 2		
Moisture Sensitivity Level (SOIC-20W)	MSL	Lev	el 3	

3. Per IPC / JEDEC J-STD-020C

Characteristic	Symbol	Min	Тур	Max	Uni
Output Voltage ($T_A = 25^{\circ}C$, $I_{out} = 1.0 \text{ mA}$)	V _{out}	4.95	5.0	5.05	V
Output Voltage (6.0 V < V_{CC} < 28 V, 1.0 mA < I_{out} < 50 mA)	V _{out}	4.9	5.0	5.1	V
Output Voltage (V _{CC} = 35 V, t < 1.0 s, 1.0 mA < I_{out} < 50 mA)	V _{out}	4.9	5.0	5.1	V
Dropout Voltage	V _{drop}				V
l _{out} = 10 mA		-	0.1	0.25	
l _{out} = 50 mA		_	0.2	0.40	
I _{out} = 100 mA		-	0.3	0.50	
Input to Output Voltage Difference in Undervoltage Condition	V _{IO}	-	0.2	0.4	V
(V _{CC} = 4.0 V, I _{out} = 35 mA)					
Line Regulation (6.0 V < V_{CC} < 28 V, I_{out} = 1.0 mA)	Reg _{line}	-	1.0	20	m٧
Load Regulation (1.0 mA < I _{out} < 100 mA)	Reg _{load}	-	8.0	30	m∖
Current Limit	I _{Lim}				mA
$V_{out} = 4.5 V$		105	200	400	
V _{out} = 0 V		-	100	-	
Quiescent Current (I _{out} = 0.3 mA, T _A < 100°C)	I _{QSE}	-	150	260	μA
Quiescent Current (I _{out} = 100 mA)	Ι _Q	-	_	5.0	mA
RESET	L	1 1			
Reset Threshold Voltage	V _{Resth}	-	4.5	-	V
Reset Threshold Hysteresis	V _{Resth,hys}				m∖
@ T _A = 25°C		50	100	200	
@ $T_A = -40$ to +125°C		50	_	300	
Reset Pulse Delay (C _T = 100 nF, $t_R \ge 100 \ \mu s$)	t _{ResD}	55	100	180	ms
Reset Reaction Time (C _T = 100 nF)	t _{ResR}	-	5.0	30	μs
Reset Output Low Voltage (R _{Reset} = 10 k Ω to V _{out} , V _{CC} \ge 3.0 V)	V _{ResL}	-	_	0.4	V
Reset Output High Leakage Current (V _{Reset} = 5.0 V)	I _{ResH}	-	_	1.0	μA
Delay Comparator Threshold	V _{CTth}	-	2.0	-	V
Delay Comparator Threshold Hysteresis	V _{CTth, hys}	-	100	-	m∖
SENSE				1	
Sense Low Threshold (V _{SI} Decreasing = 1.5 V to 1.0 V)	V _{SOth}	1.16	1.23	1.35	V
Sense Threshold Hysteresis	V _{SOth,hys}	20	100	200	m∖
Sense Output Low Voltage (V_{SI} \leq 1.16 V, V_{CC} \geq 3.0 V, R_{SO} = 10 k Ω to V_{out})	V _{SOL}	-	_	0.4	V
Sense Output Leakage (V _{SO} = 5.0 V, V _{SI} \ge 1.5 V)	I _{SOH}	_	_	1.0	μA
Sense Input Current	I _{SI}	-1.0	0.1	1.0	μA
PREREGULATOR	1			1	
Preregulator Output Voltage (I _Z = 10 μ A)	Vz	_	6.3	_	V

ELECTRICAL CHARACTERISTICS	(V _{CC} = 14 V, -40° C < T _A < 125°C, unless otherwise specified.)
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Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PIN FUNCTION DESCRIPTION

Pin SO-8, SO-8 EP	Pin SO–20 W	Symbol	Description	
1	19	V _{CC}	Supply Voltage	
2	20	SI	Input of Sense Comparator. If not used, connect to Vout.	
3	1	VZ	Output of Preregulator	
4	2	CT	Reset Delay Capacitor	
5	4–7, 14–17	GND	Ground	
6	10	Reset	Output of Reset Comparator	
7	11	S _O	Output of Sense Comparator	
8	12	V _{out}	Main Regulator Output	
-	3, 8, 9, 13, 18	NC	No Connect	

TYPICAL CHARACTERIZATION CURVES



TYPICAL CHARACTERIZATION CURVES (continued)



APPLICATION INFORMATION

Supply Voltage Transient

High supply voltage transients can cause a reset output signal perturbation. For supply voltages greater than 8.0 V the circuit shows a high immunity of the reset output against supply transients of more than 100 V/ μ s. For supply voltages

less than 8.0 V supply transients of more than 0.4 V/µs can cause a reset signal perturbation. To improve the transient behavior for supply voltages less than 8.0 V a capacitor at Pin 3 can be used. A capacitor at Pin 3 (C3 \leq 1.0 µF) also reduces the output noise.







OPERATING DESCRIPTION

The NCV4949A is a monolithic integrated low dropout voltage regulator. Several outstanding features and auxiliary functions are implemented to meet the requirements of supplying microprocessor systems in automotive applications. It is also suitable in other applications where the included functions are required. The modular approach of this device allows the use of other features and functions independently when required.

Voltage Regulator

The voltage regulator uses an isolated collector vertical PNP transistor as a regulating element. With this structure, very low dropout voltage at currents up to 100 mA is obtained. The dropout operation of the standby regulator is maintained down to 3.0 V input supply voltage. The output voltage is regulated up to a transient input supply voltage of 35 V.

A typical curve showing the standby output voltage as a function of the input supply voltage is shown in Figure 16.

The current consumption of the device (quiescent current) is less than $200 \ \mu$ A.

To reduce the quiescent current peak in the undervoltage region and to improve the transient response in this region, the dropout voltage is controlled. The quiescent current as a function of the supply input voltage is shown in Figure 17.

Short Circuit Protection:

The maximum output current is internally limited. In case of short circuit, the output current is foldback current limited as described in Figure 15.



Figure 15. Foldback Characteristic of Vout



Figure 16. Output Voltage versus Supply Voltage



Figure 17. Quiescent Current versus Supply Voltage

Preregulator

To improve transient immunity a preregulator stabilizes the internal supply voltage to 6.0 V. This internal voltage is present at Pin 3 (V_Z). This voltage should not be used as an output because the output capability is very small (\leq 100 µA).

This output may be used to improve transient behavior for supply voltages less than 8.0 V. In this case a capacitor (100 nF - 1.0 μ F) must be connected between Pin 3 and GND. If this feature is not used Pin 3 must be left open.

Reset Circuit

The block circuit diagram of the reset circuit is shown in Figure 18.

The reset circuit supervises the output voltage. The reset threshold of 4.5 V is defined by the internal reference voltage and standby output divider.

The reset pulse delay time t_{RD} , is defined by the charge time of an external capacitor C_T :

$$t_{\text{RD}} = \frac{C_{\text{T}} \times 2.0 \text{ V}}{2.0 \,\mu\text{A}}$$

The reaction time of the reset circuit originates from the discharge time limitation of the reset capacitor C_T and is proportional to the value of C_T . The reaction time of the reset circuit increases the noise immunity.



Figure 18. Reset Circuit

ORDERING INFORMATION

Output voltage drops below the reset threshold only marginally longer than the reaction time results in a shorter reset delay time.

The nominal reset delay time will be generated for output voltage drops longer than approximately 50 μ s. The typical reset output waveforms are shown in Figure 19.



Figure 19. Typical Reset Output Waveforms

Sense Comparator

The sense comparator compares an input signal with an internal voltage reference of typical 1.23 V. The use of an external voltage divider makes this comparator very flexible in the application.

It can be used to supervise the input voltage either before or after a protection diode and to provide additional information to the microprocessor such as low voltage warnings.

Device	Package	Shipping [†]
NCV4949ADR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NCV4949APDR2G	SOIC-8 EP (Pb-Free)	2500 / Tape & Reel
NCV4949ADWR2G	SOIC-20 WB (Pb-Free)	1000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.6M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE

- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07. 5.
- 6.

STANDARD 15 751-07.					
	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	1.27 BSC		0.050 BSC	
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
κ	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
s	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*





PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSIONS: MILLIMETERS

- NOTES: 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS 3. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.004mm IN EXCESS OF MAXIMUM MATERIAL CONDITION. 4. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRU-SIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR CATE PURPS SHALL NOT EXCEED A ORDER DIDE

GATE BURRS SHALL NOT EXCEED 0.006mm PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR

PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.010mm PER SIDE.

5. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

	MILLIMETERS		
DIM	MIN	MAX	
Α	1.35	1.75	
A1		0.10	
A2	1.35	1.65	
b	0.31	0.51	
b1	0.28	0.48	
С	0.17	0.25	
c1	0.17	0.23	
D	4.90	BSC	
Е	6.00	BSC	
E1	3.90	BSC	
е	1.27	BSC	
F	2.24	3.20	
G	1.55	2.51	
h	0.25	0.50	
L	0.40	1.27	
L1	1.04 REF		
θ	0 °	8 °	

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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